

**REMARKS**

Claims 1-3, claims 5-11 and new claims 12 and 13 are pending. The amendments and new claims are supported in the specification as follows: Claims 1 and 8: (canceled claim 4; published application [0039]); new claim 12: (published application [0043]); and new claim 13: (claim 8).

***Claim Objections***

**Claim 7 is objected because of a typographical error.** (Office Action p.2)

This typographical error has been corrected.

***Double Patenting***

**Claims 1-5 and 7-9 are provisionally rejected based on obviousness-type double patenting over copending application no. 10/591,706.** (Office Action p.2)

The current status of application no. 10/591,706 as of January 6, 2009 is that undergoing preexam processing. Since there is a chance that the instant application may be granted first, a terminal disclaimer would be filed in the other application, not this one. Since the rejection is provisional, it appears that nothing needs to be done at present, although the applicants are aware of the rejection.

***Claim Rejections***

**Claims 1-6 and 8-11 are rejected under 35 U.S.C. 102(b) as being anticipated by Furuta et al (US 5,891,532).** (Office Action Page 3)

Claim 1 has been amended with the subject matter of claim 4 and [0039], namely that the content of said epoxy-group containing ethylene copolymer is in a range of 0.1 to 20 parts by weight. It is stated in the specification that:

[0039] In the resin molded article of the present invention, it is preferred that a content of the epoxy-group containing ethylene copolymer is in a range of 0.1 to

25 parts by weight, and more preferably 10 to 20 parts by weight with respect to 100 parts by weight of the liquid-crystalline polyester. In this range, the heat-treatment effect of reducing the dielectric loss tangent becomes higher. When the content is less than 0.1 parts by weight, it may difficult to use the resin molded article of the invention as a circuit board because the adhesion of a metal film for circuit pattern formed thereon easily deteriorate. On the other hand, when the content is more than 25 parts by weight, heat resistance and moldability of the resin composition may deteriorate.

There are significant differences between the claimed invention and Furuta'532, including the differences that the claimed invention is directed toward a *molded article*, while Furuta'532 is directed toward gas barrier thin films capable of being blow molded, and the instant claims recite an ethylene copolymer in a range of 0.1 to 20 parts by weight, which is not disclosed in Furuta'532.

Furuta is directed toward thin films for wrapping food for use in microwave ovens. It is described in col.12, lines 60-64:

The practical thickness of the film obtainable from the liquid crystal polyester resin composition used in the present invention is not limited but preferably within a range of 1 through 500 $\mu$ m and more preferably within a range of 1 through 200 $\mu$ m.

The claimed molded article is in fact completely different than the thin films of Furuta'532.

Further, nowhere in Furuta, including the working examples, is there disclosed an ethylene copolymer in a range of 0.1 to 20 parts by weight.

Based on these differences alone, Furuta '532 cannot anticipate the invention as now claimed. It is respectfully requested that the rejection be withdrawn.

**Claims 1-3 and 8-11 are rejected under 35 U.S.C. 102(b) as being anticipated by Haider et al (US 5,216,073). (Office Action Page 5)**

Claim 1 has been amended with the subject matter of claim 4 and [0039], making this rejection now moot.

**Claim 7 is rejected under 35 U.S.C. 103(a) as being unpatentable over Furuta et al (US 5,891, 532 hereinafter referred to as '532) in view of Furuta et al (US 5,759, 674 hereinafter referred to as '674). (Office Action Page 6)**

Claim 7 is dependent on claim 1 which has been amended with the subject matter of claim 4 and [0039].

Furuta '674 also only discloses a film, as opposed to a molded resin article. Furuta'674 discloses the film thickness in col. 10, lines 12-15:

The practical thickness of the film obtainable from the liquid crystal polyester resin composition used in the present invention is in many cases within a range of 2 through 500 $\mu$ m and preferably within a range of 5 through 300 $\mu$ m.

Since claim 7 depends from claim 1, and Furuta'674 does not make up for the deficiencies of Furuta'532 as discussed above, the combination of references still does not make the invention of claim 7 obvious. It is respectfully requested that the rejection be reconsidered and withdrawn.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

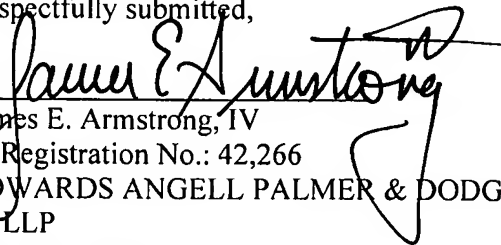
The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1105.

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Customer No. 21874

Respectfully submitted,

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